

Application No. 10/823,671

**IN THE CLAIMS:**

Please amend Claims 1-5 as follows:

**LISTING OF CURRENT CLAIMS**

1. (Currently Amended) A chassis air guide thermal cooling solution comprising a side panel, a locating plate, a locating assembly, a fan, a flexible ring and an accommodating ring; ~~and being characterized that, comprising protruding edges of a the fan are wedged at wedge grooves of a locating assembly to locate the fan in the locating assembly, locating notches of a the flexible ring are positioned in the locating assembly, an the accommodating ring is accommodated around the flexible ring, and the locating assembly are is fastened with a the locating plate to a power supply by means of screws;~~  
a the side panel is devised with ventilation openings for facilitating the fan to draw external air or to discharge hot air at an interior of the device;  
the locating assembly is provided with a plurality of flexible openings, and after having fixed the locating plate to the interior of the ~~equipment chassis~~, an assembled position of the chassis air guide thermal cooling solution is adjusted, and the locating assembly, the locating plate and a the power supply are fixed using screws; and after having assembled the chassis air guide thermal cooling solution at the interior, a distance between the accommodating ring and the heat dissipating fan is adjusted using the flexible ring, so as to further favor a user to adjust a length of the flexible ring for coordinating with equipment arrangement at the interior of the device.
2. (Original) The chassis air guide thermal cooling solution in accordance with claim 1, wherein the fan is connected with the power supply at the interior of the device via a power line.

Application No. 10/823,671

3. (Currently Amended) The chassis air guide thermal cooling solution in accordance with claim 1, wherein the side panel is devised to have dimensions the same as those of the device.
4. (Original) The chassis air guide thermal cooling solution in accordance with claim 1, wherein the accommodating ring is an accommodating ring having a size corresponding to that of the heat dissipating fan at the interior of the device.
5. (Currently Amended) The chassis air guide thermal cooling solution in accordance with claim 1, wherein a combined structure of a wedge opening and the locating plate is devised as a snap closure, a spring closure or a wedge structure applied in an interior of the computer, electronic and electromechanical products.